Docket No.: Q78432

DECLARATION AND POWER OF ATTORNEY FOR UTILITY OR DESIGN PATENT APPLICATION (37 CFR 1.63)

As a below named inventor, I hereby declare that: My residence, mailing address, and citizenship are as attend below next to my name. I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) I the subject matter which is claimed and for which a patent is sought on the invention entitled:

HIGH DENSITY CHIP SCALE LEADFRAME PACKAGE AND METHOD OF MANUFACTURING THE PACKAGE

the application of which		•			
is attached hereto	OR	was filed on			
		as United States Application Number or PCT International Application Number			
		and was amended on			
	•	(if applicable).			
I hereby state that I have reviewed by any amendment specifically ref	I and understand the con	ateats of the above identified application	a, including the claims, as amended		
I acknowledge the duty to disc continuation-in-part application(s) the national or PCT international for	, material information v	n is material to patentability as define which became available between the fills ation-in-part application.	ed in 37 CFR 1.56, including for ag date of the prior application and		
breeder's rights certificate(s), or 3 United States of America, listed 1	65(a) of any PCT interroction and have also ide to certificate(s), or any	or (f), or 365(b) of any foreign applicated the state of	at least one country other than the		
Prior Application Number(s)	Country	y Filiog Date	Priority Claimed Yes No		
I hereby claim benefit under 35 Un	ited States Code §119(e) of any United States provisional applic	ation(s) listed below.		
	Application Number(#)	Filing Dute	•		
	60/429,315	•	November 27, 2002		
application(s) designating the Unit not disclosed in a listed prior Units United States Code, §112, I acknowledge	ed States, listed below a d States or PCT Interna- owledge my duty to dis	of any United States application(s) or nd, insolar as the subject matter of each tional application in the manner provider sclose any information material to the ag date of the prior application and the	of the claims of this application is d by the first paragraph of Title 35, patentability of this application as		
Prior U.S. or International Applicat	ian Number(s)	U.S. or International Filing Date	Status		
		N. Carlotte			

I hereby appoint all attorneys of SUGHRUE MION, PLLC who are listed under the USPTO Customer Number shown below as my attorneys to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith, recognizing that the specific attorneys listed under that Customer Number may be changed from time to time at the sole discretion of Sughrue Mion, PLLC, and request that all correspondence about the application be addressed to the address filed under the same USPTO Customer Number.

WASHINGTON OFFICE

23373

CUSTOMER NUMBER

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

[Page 1 of 2]

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SUGHRUE MION

13:19 NOV-21-2003

AM. A MINI

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